L	Hits	Search Text	DB	Time stamp
Number				
2	159	313/\$.ccls. and corrugated	USPAT;	2003/06/16
			EPO; JPO	07:18
3	32	313/\$.ccls. and corrugated and substrate	USPAT;	2003/06/16
<u> </u>			EPO; JPO	07:24
1	907	313/506.ccls.	USPAT;	2003/06/16
			EPO; JPO	11:17
4	2498	corrugated and substrate and light	USPAT;	2003/06/16
			EPO; JPO	07:24
5	181	corrugated and substrate and "light	USPAT;	2003/06/16
		emitting"	EPO; JPO	07:24
14	6	313/506.ccls. and (texture)	USPAT;	2003/06/16
			EPO; JPO	08:08
15	4	313/506.ccls. and (textured)	USPAT;	2003/06/16
			EPO; JPO	08:11
16	75	313/506.ccls. and (uneven)	USPAT;	2003/06/16
			EPO; JPO	08:11
23	256	257/95.ccls.	USPAT;	2003/06/16
			EPO; JPO	08:25
24	1301	257/98.ccls.	USPAT;	2003/06/16
			EPO; JPO	08:25
49	1114	(IWATA nearl HIROSHI).in.	USPAT;	2003/06/16
			EPO; JPO	10:32
50	272	(IWATA near1 HIROSHI).in. and	USPAT;	2003/06/16
		semiconductor	EPO; JPO	10:32
51	716	313/504.ccls.	USPAT;	2003/06/16
			EPO; JPO	11:17
52	243	313/498.ccls.	USPAT;	2003/06/16
			EPO; JPO	11:17

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